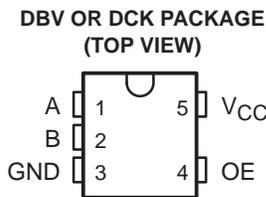


- 5-Ω Switch Connection Between Two Ports
- CMOS-Compatible Control Input Levels
- Package Options Include Plastic Small-Outline Transistor (DBV, DCK) Packages



description

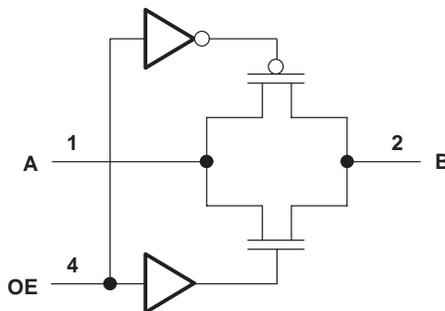
The SN74CBT1G66 features a single high-speed line switch. The switch is disabled when the output-enable (OE) input is low.

The SN74CBT1G66 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUT OE	FUNCTION
H	A port = B port
L	Disconnect

logic diagram (positive logic)



PRODUCT PREVIEW



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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SN74CBT1G66

SINGLE FET BUS SWITCH

SCDS110 – JULY 2000

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	206°C/W
DCK package	252°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.3	5.5	V
$V_{I/O}$	I/O port voltage	0	V_{CC}	V
V_{IH}	High-level input voltage	$0.7 \times V_{CC}$		V
V_{IL}	Low-level input voltage	$0.3 \times V_{CC}$		V
V_{IN}	Control input voltage	0	5.5	V
t_r/t_f	Control input transition rise/fall time	$V_{CC} = 2.3 \text{ V to } 3.6 \text{ V}$		ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		
T_A	Operating free-air temperature	–40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	MIN	TYP‡	MAX	UNIT
V_{IK}	$I_I = -18 \text{ mA}$		4.5 V			–1.2	V
I_I	$0 \leq V_I \leq 5.5 \text{ V}$		0 to 5.5 V			± 1	μA
I_{off}	$0 \leq A \text{ or } B \leq 4.5 \text{ V}$		$V_{CC} = 0$			10	μA
I_{OZ}	$0 \leq A \text{ or } B \leq V_{CC}$		2.3 V to 5.5 V			± 10	μA
r_{on}	$V_I = 0$	$I_I = 8 \text{ mA}$	2.3 V	5	12	Ω	
	$V_I = 2.3 \text{ V}$			13	30		
	$V_I = 0$	$I_I = 24 \text{ mA}$	3 V	4	9		
	$V_I = 3 \text{ V}$			10	20		
	$V_I = 0,$	$I_I = 30 \text{ mA}$	4.5 V	3	7		
	$V_I = 2.4 \text{ V},$			$I_I = 15 \text{ mA}$	5		12
$V_I = 4.5 \text{ V},$	$I_I = 30 \text{ mA}$			7	15		
I_{CC}	$V_I = V_{CC} \text{ or } \text{GND}$	$I_O = 0$	5.5 V			10	μA
C_i			0				pF
C_{io}			5 V				pF

‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.

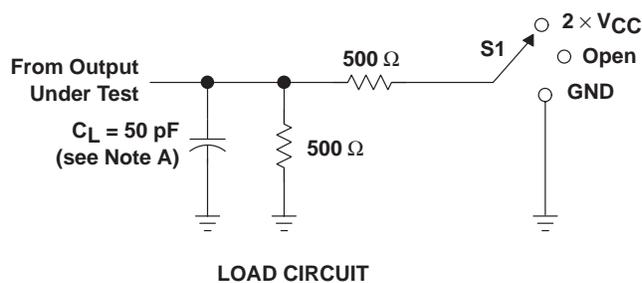
PRODUCT PREVIEW



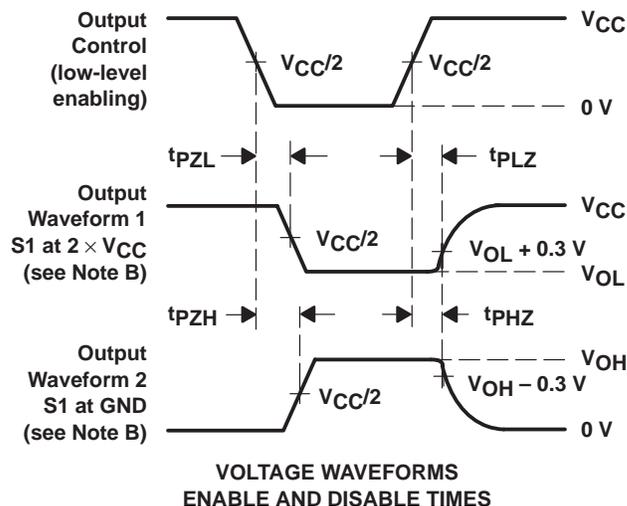
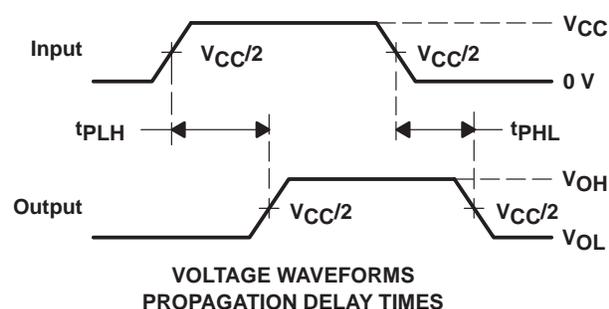
switching characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	B or A							ns
t_{en}	OE	A or B							ns
t_{dis}									

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd} t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	Open $2 \times V_{CC}$ GND



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
 - D. The output is measured with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PRODUCT PREVIEW

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